

PART INFORMATION

Mfg Item Number	P3041NXN7NNC
Mfg Item Name	FCPBGA 1295 37.5SQ3.55P1

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2016-07-06
Response Document ID	8404K50008S283A1.8
Contact Name	Freescale Semiconductor Inc
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DECLARATION

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	P3041NXN7NNC
Mfg Item Name	FCPBGA 1295 37.5SQ3.55P1
Version	ALL
Weight	13.973900
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	245 C
Max Time at Peak Temperature	30 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Bonding Agent	0.0115						g				
Bonding Agent		Solvents, additives, and other materials	Siloxanes and silicones, di-Me, vinyl group-terminated	68083-19-2		0.005175	g	450000	45	370	0.037
Bonding Agent		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.0046	g	400000	40	329	0.0329
Bonding Agent		Solvents, additives, and other materials	Dimethylsilylated and trimethylsilylated silica	68988-89-6		0.001725	g	150000	15	123	0.0123
Heat Spreader	7.532						g				
Heat Spreader		Metals	Copper, metal	7440-50-8		7.50778462	g	996785	99.6785	837292	53.7292
Heat Spreader		Nickel (external applications only)	Nickel	7440-02-0		0.02421538	g	3215	0.3215	1732	0.1732
Die Encapsulant, Filler	1.8864						g				
Die Encapsulant, Filler		Metals	Aluminum, metal	7429-90-5		1.358208	g	720000	72	97196	9.7196
Die Encapsulant, Filler		Solvents, additives, and other materials	Proprietary Material-Other siloxanes and silicones	-		0.169776	g	90000	9	12149	1.2149
Die Encapsulant, Filler		Metals	Zinc oxide	1314-13-2		0.339552	g	180000	18	24299	2.4299
Die Encapsulant, Filler		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.018864	g	10000	1	1349	0.1349
Solder Balls - Lead Free	1.2821						g				
Solder Balls - Lead Free		Metals	Copper, metal	7440-50-8		0.00642204	g	5009	0.5009	459	0.0459
Solder Balls - Lead Free		Metals	Silver, metal	7440-22-4		0.03853223	g	30054	3.0054	2757	0.2757
Solder Balls - Lead Free		Metals	Tin, metal	7440-31-5		1.23714573	g	964937	96.4937	88532	8.8532
Underfill	0.0657						g				
Underfill		Bismuth/Bismuth Compounds	Bismuth nitrate	10361-44-1		0.0003285	g	5000	0.5	23	0.0023
Underfill		Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.0003285	g	5000	0.5	23	0.0023
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27610-48-6		0.009855	g	150000	15	705	0.0705
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.00657	g	100000	10	470	0.047
Underfill		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.0003285	g	5000	0.5	23	0.0023
Underfill		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.001971	g	30000	3	141	0.0141
Underfill		Glass	Silica, vitreous	60676-86-0		0.03942	g	600000	60	2820	0.282
Underfill		Solvents, additives, and other materials	Proprietary Material-Other miscellaneous substances.	-		0.0003285	g	5000	0.5	23	0.0023
Underfill		Solvents, additives, and other materials	Proprietary Material-Other aliphatic amine compounds	-		0.00657	g	100000	10	470	0.047
Pb-free Bumped Semiconductor D	0.9392						g				
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.001966	g	5000	0.5	140	0.014
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4		0.0012858	g	3150	0.315	88	0.0088
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.03414942	g	86850	8.685	2443	0.2443
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.0035388	g	9000	0.9	253	0.0253
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-		0.3523072	g	896000	89.6	25211	2.5211
Organic Substrate, Halogen-free	2.803						g				
Organic Substrate, Halogen-free		Metals	Proprietary Material-Other aluminum compounds	-		0.0008409	g	30	0.003	6	0.0006
Organic Substrate, Halogen-free		Metals	Barium sulfate	7727-43-7		0.027945	g	9934	0.9934	1992	0.1992
Organic Substrate, Halogen-free		Metals	Copper, metal	7440-50-8		1.39273221	g	496872	49.6872	99566	9.9566
Organic Substrate, Halogen-free		Plastics/polymers	Epikote 802	28064-14-4		0.00327636	g	72521	7.2521	14546	1.4546
Organic Substrate, Halogen-free		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.1019339	g	36366	3.6366	7294	0.7294
Organic Substrate, Halogen-free		Metals	Talc	14807-96-6		0.00319822	g	1141	0.1141	228	0.0228
Organic Substrate, Halogen-free		Solvents, additives, and other materials	Proprietary Material-Other organic phosphorous compounds	-		0.03137959	g	11195	1.1195	2245	0.2245
Organic Substrate, Halogen-free		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.04298961	g	15337	1.5337	3076	0.3076
Organic Substrate, Halogen-free		Plastics/polymers	Proprietary Material-Other polymers	-		0.08639687	g	30823	3.0823	6182	0.6182
Organic Substrate, Halogen-free		Glass	Fibrous-glass-wool	65997-17-3		0.42912809	g	153096	15.3096	30709	3.0709
Organic Substrate, Halogen-free		Glass	Silicon dioxide	7631-86-9		0.38528654	g	101779	10.1779	20415	2.0415
Organic Substrate, Halogen-free		Metals	Silver, metal	7440-22-4		0.00022424	g	80	0.008	16	0.0016
Organic Substrate, Halogen-free		Metals	Tin, metal	7440-31-5		0.00681409	g	2431	0.2431	487	0.0487
Organic Substrate, Halogen-free		Plastics/polymers	Proprietary Material-Other acrylic resins	-		0.05629217	g	19989	1.9989	4009	0.4009
Organic Substrate, Halogen-free		Metals	Aluminum Hydroxide	21645-61-2		0.13551384	g	48346	4.8346	9697	0.9697
Organic Substrate, Halogen-free		Metals	Copper phthalocyanine	147-14-8		0.00016818	g	60	0.006	12	0.0012

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/P3041NXN7NNC_IPC1752_v11.xml

http://www.freescale.com/mcdfs/P3041NXN7NNC_IPC1752A.xml